PRODUCTS COVERED BY THIS RoHS DECLARATION

Haydon Kerk Motion Solutions, Inc (Haydon) is committed to comply with the European Union's "Reduction of Hazardous Substances" (RoHS) initiative to ensure our customers maintain their global presence and competitiveness with our products.

Currently all of Haydon's motor, lead screw assembly and linear rail products comply with the European Union's "Reduction of Hazardous Substances" (EU-RoHS) initiative and that no exemptions were applied to make this unit compliant. If required, our packing slips can be stamped to declare that the products shipped are RoHS compliant and may be used as objective evidence of compliance.

DECLARATIONS

As of November 1, 2005 Haydon Kerk Motion Solutions, Inc. began providing RoHS compliant product to our customers, as of January 1, 2011 Haydon currently complies to the following

1) RoHS Compliance for Restricted Materials:
Item(s) complies with RoHS Requirements, defined above, and does NOT use any RoHS exemptions noted below:

RoHS 2 exemptions:

Exemptions Expected to Expire or Change 31 December, 2010*

1-4. Mercury in fluorescent lamps per 1 July 2006 limits.
8(c). Cadmium in platings.
11(a). Lead used in C-press compliant pin connector systems.
14. Lead in solders consisting of more than two elements for the connection between the pins and the package of microprocessors with a lead content of more than 80% and less than 85% by weight.
23. Lead in finishes of fine pitch components other than connectors with a pitch of 0.65 mm and less.

Exemptions Expected to Expire 31 December 2011*

20. Lead oxide in glass used for bonding front and rear substrates of flat fluorescent lamps used for Liquid Crystal Displays (LCD).

Exemptions Expected to Expire 30 June 2012*

7(c)(III). Lead in dielectric ceramic in capacitors for a voltage of less than 125 V AC or 250 V DC.
8(a). Cadmium and its compounds in one shot pellet type thermal cut-offs.

Exemptions Expected to Expire 30 June 2014*

1. Mercury in single capped fluorescent lamps (no mercury allowed)
2(a). Mercury in double-capped linear fluorescent lamps for general lighting purposes (no mercury allowed)
2(b). Mercury in other fluorescent lamps (no mercury allowed)
3. Mercury (Hg) in cold cathode fluorescent lamps and external electrode fluorescent lamps (CCFL and EEFL) (no mercury allowed)
4. Mercury in other High Pressure Sodium (vapour) lamps for general lighting purposes
4(a). Mercury in other low pressure discharge lamps (no mercury allowed)
4(b). Mercury in High Pressure Sodium (vapour) lamps for general lighting purposes in lamps with improved colour rendering index > 60 (no mercury allowed)
4(b)-II Mercury in High Pressure Mercury (vapour) lamps except for general lighting (HMPV)
4(b)-III Mercury in metal halide lamps (MH)
4(c) Mercury in other discharge lamps for special purposes not specifically mentioned in this Declaration
5. Lead in glass of fluorescent tubes not exceeding 0.2% by weight

6. Lead in steel, aluminum, and copper alloys
   6(a). Lead as an alloying element in steel for machining purposes and in galvanized steel containing up to 0.35% lead by weight.
   6(b). Lead as an alloying element in aluminum containing up to 0.4% lead by weight.
   6(c). Lead in copper alloys containing up to 4% lead by weight.

7(a). Lead in high melting temperature type solders (i.e. lead-based alloys containing 85% by weight or more lead).

7(b). Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signaling, transmission as well as network management for telecommunications.

7(c): Electronic components with lead in a glass or ceramic matrix compound
   7(c)-I. Electrical and electronic components other than dielectric ceramic in capacitors, containing lead in a glass or ceramic matrix compound, (e.g. piezoelectronic devices)
   7(c)-II. Lead in dielectric ceramic in capacitors for a voltage of 125 V AC or 250 V DC or higher

8(b). Cadmium and its compounds in electrical contacts.

9(b). Lead in bearing shells and bushes for refrigerant-containing compressors for heating, ventilation, air conditioning and refrigeration (HVACR) applications.

11(b). Lead used in compliant pin connector systems other than C-press connector systems.

13(a). Lead in white glasses used for optical applications.

13(b). Cadmium and lead in filter glasses.

15. Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit flip chip packages.

3) Use of new RoHS materials: *It is expected that the use of these materials to be restricted in the EU by 1 January 2012*

HBCDD – Hexabromocyclododecane, CAS# 25637-99-4, 3194-55-6
NOT used in amounts greater than 0.1% (1,000 ppm) by weight, in any homogenous materials

DEHP – Bis (2-ethylhexyl) phthalate, CAS# 117-81-7
NOT used in amounts greater than 0.1% (1,000 ppm) by weight, in any homogenous materials

BBP – Butyl benzyl phthalate, CAS# 85-68-7
NOT used in amounts greater than 0.1% (1,000 ppm) by weight, in any homogenous materials

DBP – Dibutylphthalate, CAS# 84-74-2
NOT used in amounts greater than 0.1% (1,000 ppm) by weight, in any homogenous materials

Questions or requests for additional information may be directed to Rich Lyga, (203) 756-7441, ext 293, or by email at rich.lyga@ametek.com

Respectfully,

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